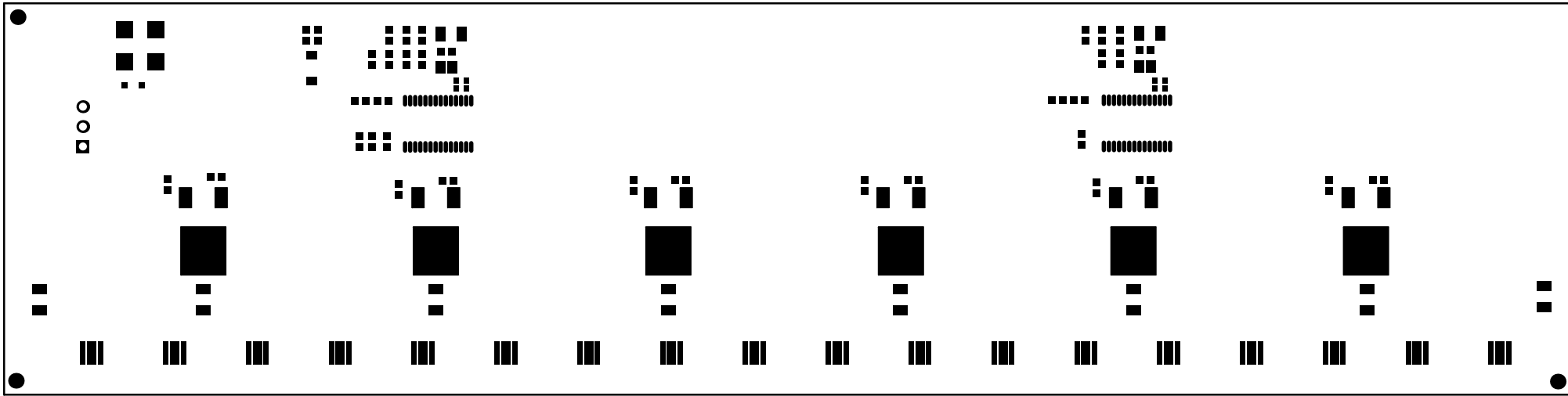
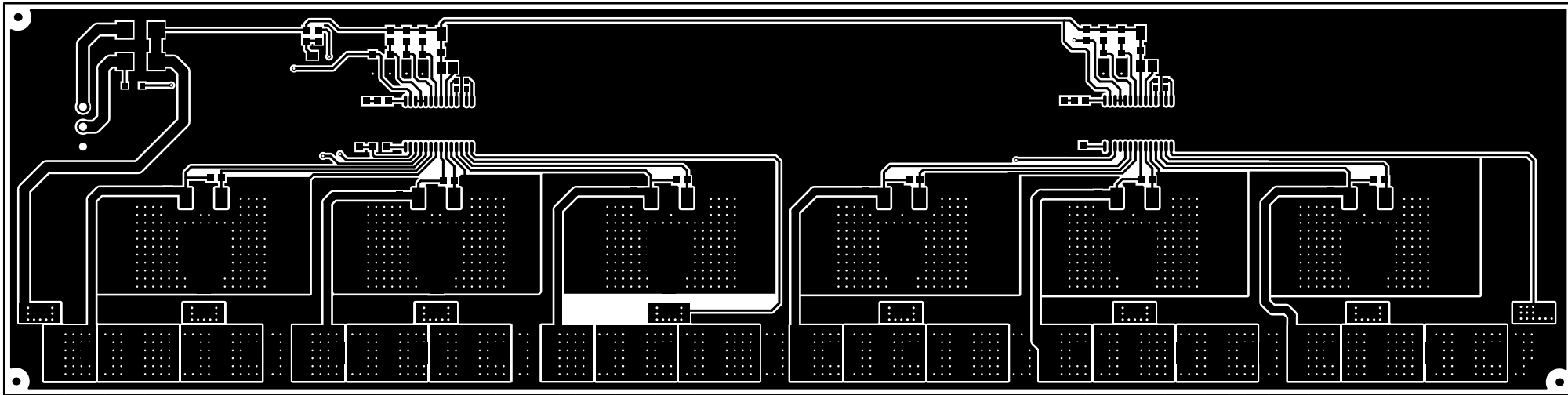


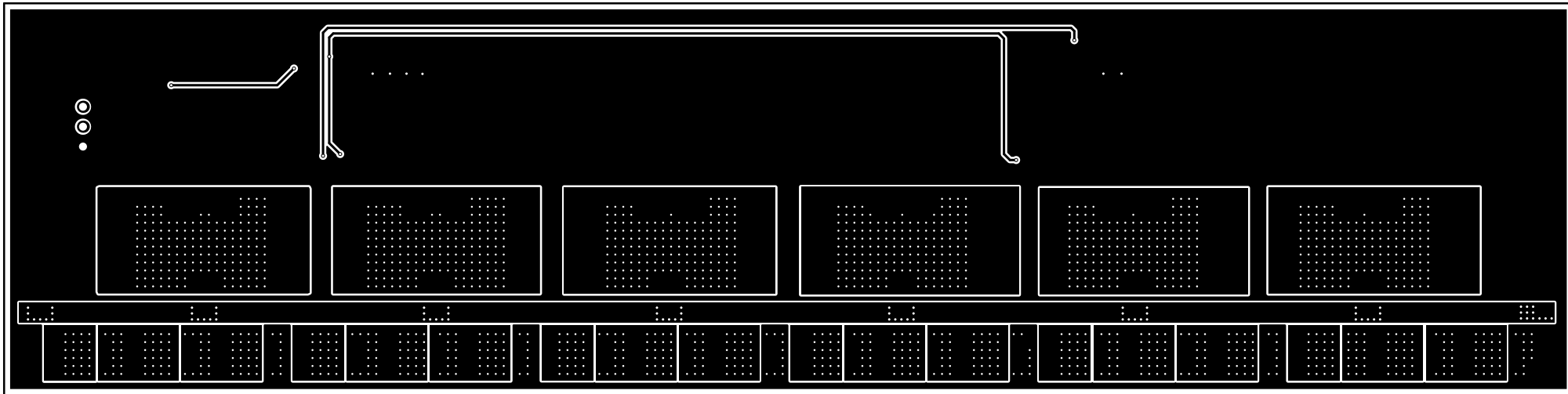
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01374		
PLOT NAME = Top Overlay	GENERATED : 3/27/2018 10:00:11 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01374		
PLOT NAME = Top Solder Mask	GENERATED : 3/27/2018 10:00:12 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01374		
PLOT NAME = Top Layer	GENERATED : 3/27/2018 10:00:13 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01374		
PLOT NAME = Bottom Layer	GENERATED : 3/27/2018	10:00:14 PM	TEXAS INSTRUMENTS

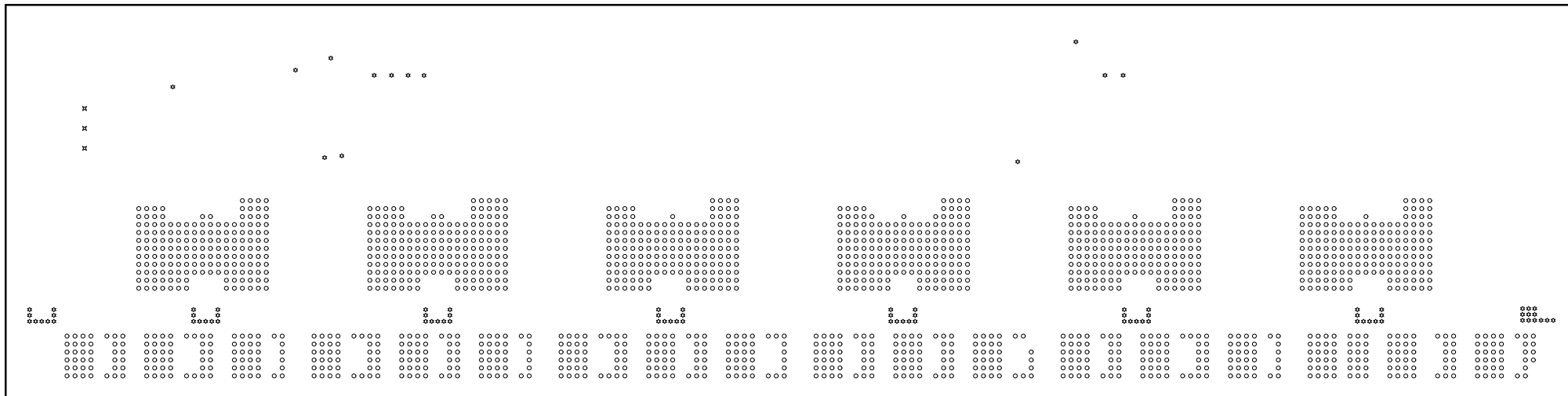
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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01374		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/27/2018 10:00:15 PM	TEXAS INSTRUMENTS	

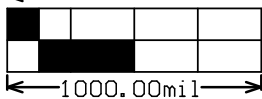


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01374		
PLOT NAME = Bottom Overlay	GENERATED : 3/27/2018 10:00:16 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	1684	10,00mil (0,254mm)	PTH	Round
✳	88	12,00mil (0,305mm)	PTH	Round
✳	3	40,16mil (1,020mm)	PTH	Round
	1775 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01374		
PLOT NAME = Drill Drawing	GENERATED : 3/27/2018	10:00:18 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01374		
PLOT NAME = Board Dimensions	GENERATED : 3/27/2018 10:00:19 PM	TEXAS INSTRUMENTS	

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